$\mathcal{N}_{\varepsilon \omega} \mathcal{I}_{\text {rise }}$ Semi-Conductor $\mathfrak{P}_{\text {roducts, }}$ Inc.

## KBPG10,15,25,35 SERIFS

## MECHANICAL DATA

Case: Molded plastic with heatsink integrally mounted in the bridge encapsulation
Terminals: Either plated .25 " $(6.35 \mathrm{~mm})$ Fasten or plated copper leads 040 " ( 1.02 mm ) diameter. Suffix letter "W" added to indicate leads. Weight: .706 ounce, 20 grams
Mounting Position: Bolt down on heat-sink with silicone thermal compound between bridge and mounting surface for maximum heat transfer efficiency.
Mounting Torque: 20 in Ib. max.
Polarity: Polarity symbols molded on body

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at $25^{\circ} \mathrm{C}$ ambient temperature unless otherwise specified; resistive or inductive load at 60 Hz .


Notes: 1 Thermal Resestence from Junction to Case for total bridge


